COMPLIANT



## Vishay Semiconductors

# HEXFRED® Ultrafast Soft Recovery Diode, 140 A



PRIMARY CHARACTERISTICS					
$V_{R}$	1200 V				
V <sub>F</sub> (typical)	2.8 V				
t <sub>rr</sub> (typical)	48 ns				
I <sub>F(DC)</sub> at T <sub>C</sub> , per module	140 A at 74 °C				
$I_{F(AV)}$ at $T_C$ , per module	140 A at 46 °C				
Package	SOT-227				

#### **FEATURES**

- · Fast recovery time characteristic
- · Electrically isolated base plate
- Large creepage distance between terminal
- · Simplified mechanical designs, rapid assembly
- Designed and qualified for industrial level
- UL approved file E78996
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### **DESCRIPTION / APPLICATIONS**

The dual diode series configuration VS-HFA140FA120 is used for output rectification or freewheeling/clamping operation and high voltage application.

The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built.

These modules are intended for general applications such as HV power supplies, electronic welders, motor control and inverters.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS		
Cathode to anode voltage	$V_R$		1200	V		
Continuous forward current per leg	l <sub>E</sub>	T <sub>C</sub> = 74 °C	70	А		
per module			140			
Single pulse forward current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	350			
Maximum power dissipation, per leq	$P_{D}$	T <sub>C</sub> = 25 °C	357	W		
Maximum power dissipation, per leg		T <sub>C</sub> = 100 °C	143			
RMS isolation voltage	V <sub>ISOL</sub>	Any terminal to case, t = 1 minute	2500	V		
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C		

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	$V_{BR}$	I <sub>R</sub> = 100 μA	1200	-	-		
Forward voltage, per leg		I <sub>F</sub> = 60 A	-	2.8	4.0	V	
	M	I <sub>F</sub> = 120 A	-	3.6	5.3		
	V <sub>FM</sub>	I <sub>F</sub> = 60 A, T <sub>J</sub> = 125 °C	-	2.7	-		
		I <sub>F</sub> = 60 A, T <sub>J</sub> = 150 °C	-	2.65	-		
		V <sub>R</sub> = V <sub>R</sub> rated	-	2.0	75	μΑ	
Reverse leakage current, per leg	I <sub>RM</sub>	$T_J = 125 ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	1.6	5	A	
		T <sub>J</sub> = 150 °C, V <sub>B</sub> = V <sub>B</sub> rated	-	5	10	mA	



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
	t <sub>rr</sub>	$I_F = 1 A$ ; $dI_F/dt = 200 A/\mu s$ ; $V_R = 30 V$		-	48	ı	
Reverse recovery time, per leg		T <sub>J</sub> = 25 °C	$I_F = 50 \text{ A}$ $dI_F/dt = -200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	145	-	ns A
		T <sub>J</sub> = 125 °C		-	218	-	
Deals assessed assessed assessed	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	13	-	
Peak recovery current, per leg		T <sub>J</sub> = 125 °C		-	18	-	
Reverse recovery charge, per leg	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	910	-	nC
		T <sub>J</sub> = 125 °C		-	1920	-	
Junction capacitance, per leg	C <sub>T</sub>	V <sub>R</sub> = 1200 V		-	27	-	pF

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction to case, single leg conducting	В		-	-	0.35	
Junction to case, both legs conducting	R <sub>thJC</sub>		-	-	0.175	°C/W
Case to heatsink	R <sub>thCS</sub>	Flat, greased surface	-	0.05	-	1
Weight			-	30	-	g
Mounting toward		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
Mounting torque		Torque to heatsink	-	-	1.8 (15.9)	Nm (lbf.in)
Case style				5	SOT-227	

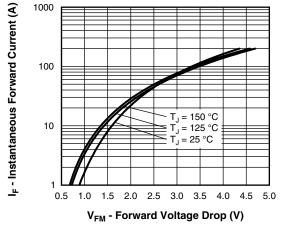


Fig. 1 - Typical Forward Voltage Drop Characteristics

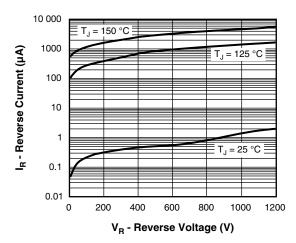


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

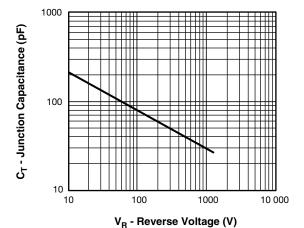


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage



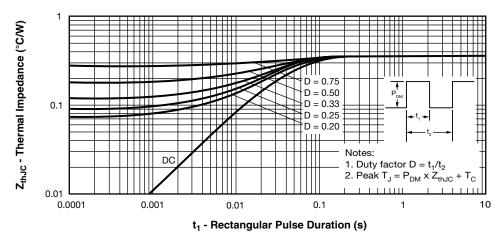


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)

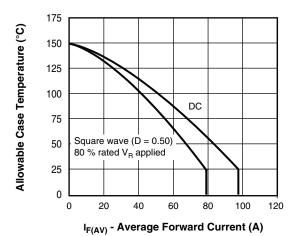


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

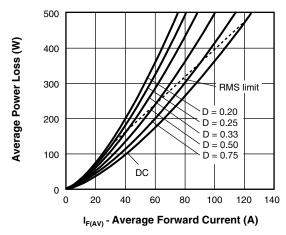


Fig. 6 - Forward Power Loss Characteristics

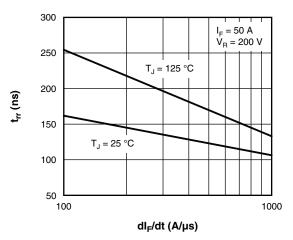


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

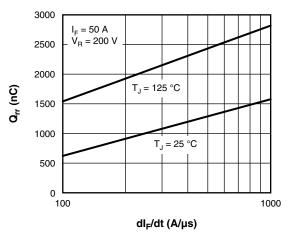


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

(1) Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;  $Pd = forward power loss = I_{F(AV)} \times V_{FM} at (I_{F(AV)}/D)$  (see fig. 5);  $Pd_{REV} = inverse power loss = V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = rated V_R$ 

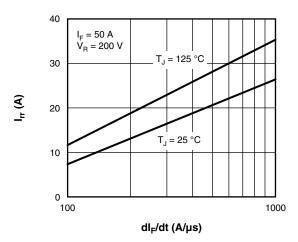


Fig. 9 - Typical Peak Recovery Current vs. dl<sub>F</sub>/dt

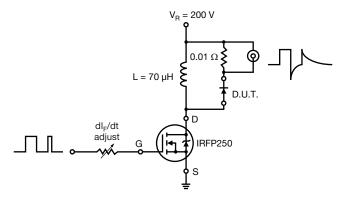
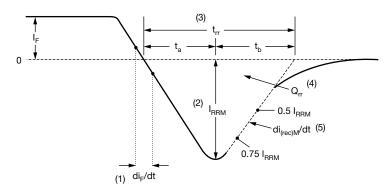


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_{rr}$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\boldsymbol{Q}_{rr}$  area under curve defined by  $\boldsymbol{t}_{rr}$  and  $\boldsymbol{I}_{RRM}$

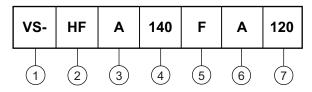
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 11 - Reverse Recovery Waveform and Definitions

#### **ORDERING INFORMATION TABLE**

**Device code** 



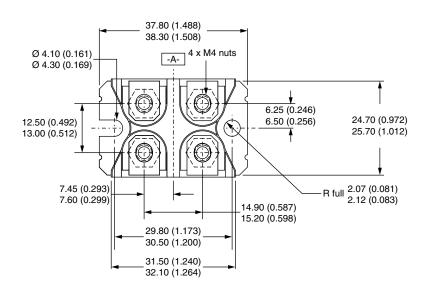
- 1 Vishay Semiconductors product
- 2 HEXFRED® family
- Process designator (A = electron irradiated)
- 4 Average current (140 = 140 A)
- 5 Circuit configuration (two separate diodes, parallel pin-out)
- 6 Package indicator (SOT-227 standard insulated base)
- 7 Voltage rating (120 = 1200 V)

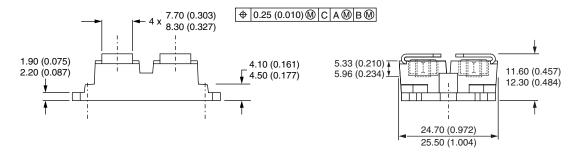
CIRCUIT CONFIGURATION						
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING				
Two separate diodes, parallel pin-out	F	Lead Assignment  4 0 0 3 4 1 0 0 2 1				

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95423				
Part marking information	www.vishay.com/doc?95425				

## SOT-227 Generation 2

### **DIMENSIONS** in millimeters (inches)





#### Note

· Controlling dimension: millimeter



## **Legal Disclaimer Notice**

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